

LINEAR TECHNOLOGY MATERIALS DECLARATION

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(Engineering Calculation)

QFN 5mm X 7mm Exp. Pad

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TOTAL MASS (g) : 0.08954

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.002920 | 1000000 | 32611.1757812 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.037381 | 975000 | 417478.875 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000920 | 24000 | 10274.7539062 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000012 | 300 | 134.018539429 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000027 | 700 | 301.541717529 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.038340 | 1000000 | 428189.1875 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.001850 | 1000000 | 20659.5351562 | | |
| | | External Plating Total: | | | | 0.001850 | 1000000 | 20659.5351562 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000831 | 1000000 | 9280.78320312 | | |
| | | Internal Plating Total: | | | | 0.000831 | 1000000 | 9280.78320312 |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.001187 | 750000 | 13256.6660156 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000396 | 250000 | 4422.61132812 | | |
| Die Attach Total: | | | | 0.001583 | 1000000 | 17679.2773438 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.005689 | 130000 | 63535.9492188 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.037634 | 860000 | 420304.4375 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000438 | 10000 | 4891.67626953 | | |
| | | Encapsulation Total: | | | | 0.043761 | 1000000 | 488732.0625 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000255 | 1000000 | 2847.89355469 | | |
| | | | | | TOTAL MASS (g) : | 0.08954 | | |